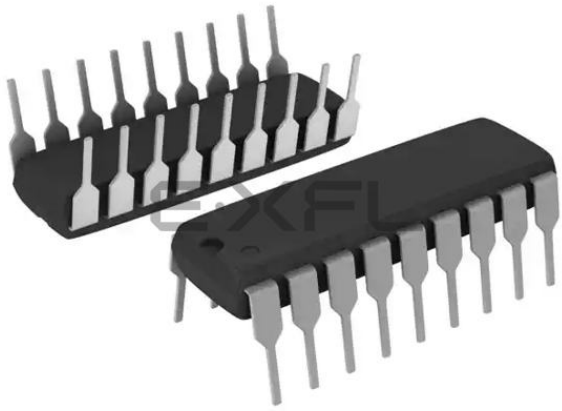

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lce624-04e-p

1.0 GENERAL DESCRIPTION

The PIC16CE62X are 18 and 20-Pin EPROM-based members of the versatile PIC® family of low-cost, high-performance, CMOS, fully-static, 8-bit microcontrollers with EEPROM data memory.

All PIC® microcontrollers employ an advanced RISC architecture. The PIC16CE62X family has enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with separate 8-bit wide data. The two-stage instruction pipeline allows all instructions to execute in a single-cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16CE62X microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The PIC16CE623 and PIC16CE624 have 96 bytes of RAM. The PIC16CE625 has 128 bytes of RAM. Each microcontroller contains a 128x8 EEPROM memory array for storing non-volatile information, such as calibration data or security codes. This memory has an endurance of 1,000,000 erase/write cycles and a retention of 40 plus years.

Each device has 13 I/O pins and an 8-bit timer/counter with an 8-bit programmable prescaler. In addition, the PIC16CE62X adds two analog comparators with a programmable on-chip voltage reference module. The comparator module is ideally suited for applications requiring a low-cost analog interface (e.g., battery chargers, threshold detectors, white goods controllers, etc).

PIC16CE62X devices have special features to reduce external components, thus reducing system cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low-cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (power-down) mode offers power savings. The user can wake-up the chip from SLEEP through several external and internal interrupts and reset.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lock- up.

A UV-erasable CERDIP-packaged version is ideal for code development, while the cost-effective One-Time Programmable (OTP) version is suitable for production in any volume.

Table 1-1 shows the features of the PIC16CE62X mid-range microcontroller families.

A simplified block diagram of the PIC16CE62X is shown in Figure 3-1.

The PIC16CE62X series fits perfectly in applications ranging from multi-pocket battery chargers to low-power remote sensors. The EPROM technology makes customization of application programs (detection levels, pulse generation, timers, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low-cost, low-power, high-performance, ease of use and I/O flexibility make the PIC16CE62X very versatile.

1.1 Development Support

The PIC16CE62X family is supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a low-cost development programmer and a full-featured programmer. A “C” compiler is also available.

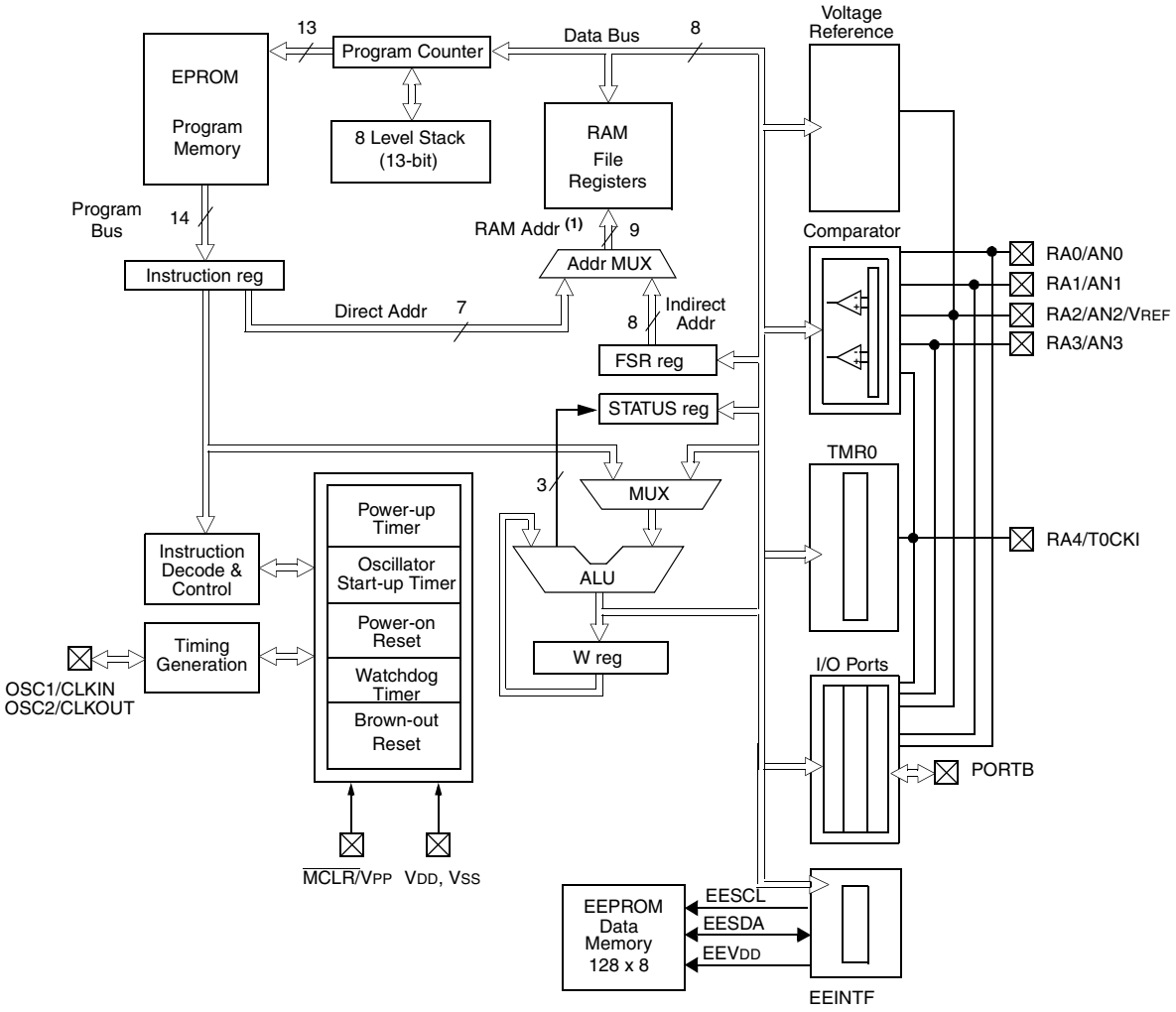
TABLE 1-1: PIC16CE62X FAMILY OF DEVICES

		PIC16CE623	PIC16CE624	PIC16CE625
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2K
	Data Memory (bytes)	96	96	128
Peripherals	EEPROM Data Memory (bytes)	128	128	128
	Timer Module(s)	TMR0	TMR0	TMR0
	Comparators(s)	2	2	2
	Internal Reference Voltage	Yes	Yes	Yes
Features	Interrupt Sources	4	4	4
	I/O Pins	13	13	13
	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5
	Brown-out Reset	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.
All PIC16CE62X Family devices use serial programming with clock pin RB6 and data pin RB7.

FIGURE 3-1: BLOCK DIAGRAM

Device	Program Memory	Data Memory (RAM)	EEPROM DATA MEMORY
PIC16CE623	512 x 14	96 x 8	128 x 8
PIC16CE624	1K x 14	96 x 8	128 x 8
PIC16CE625	2K x 14	128 x 8	128 x 8



Note 1: Higher order bits are from the STATUS register.

4.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions for controlling the desired operation of the device (Table 4-1). These registers are static RAM.

The special registers can be classified into two sets (core and peripheral). The Special Function Registers associated with the “core” functions are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

TABLE 4-1: SPECIAL REGISTERS FOR THE PIC16CE62X

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other resets(1)
Bank 0											
00h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
01h	TMR0	Timer0 Module’s Register								xxxx xxxx	uuuu uuuu
02h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
03h	STATUS	IRP(2)	RP1(2)	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
04h	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
05h	PORTA	—	—	—	RA4	RA3	RA2	RA1	RA0	---x 0000	---u 0000
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
07h	Unimplemented									–	–
08h	Unimplemented									–	–
09h	Unimplemented									–	–
0Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of program counter					---0 0000	---0 0000
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	-0-- ----	-0-- ----
0Dh-1Eh	Unimplemented									–	–
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
Bank 1											
80h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
81h	OPTION	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
83h	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
84h	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
87h	Unimplemented									–	–
88h	Unimplemented									–	–
89h	Unimplemented									–	–
8Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of program counter					---0 0000	---0 0000
8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	-0-- ----	-0-- ----
8Dh	Unimplemented									–	–
8Eh	PCON	—	—	—	—	—	—	$\overline{POR}$	$\overline{BOD}$	---- --0x	---- --uq
8Fh-9Eh	Unimplemented									–	–
90h	EEINTF	—	—	—	—	—	EESCL	EESDA	EEVDD	---- -111	---- -111
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000

Legend: — = Unimplemented locations read as ‘0’, u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

Note 1: Other (non power-up) resets include $\overline{MCLR}$ reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

Note 2: IRP & RPI bits are reserved; always maintain these bits clear.

NOTES:

FIGURE 5-3: BLOCK DIAGRAM OF RA3 PIN

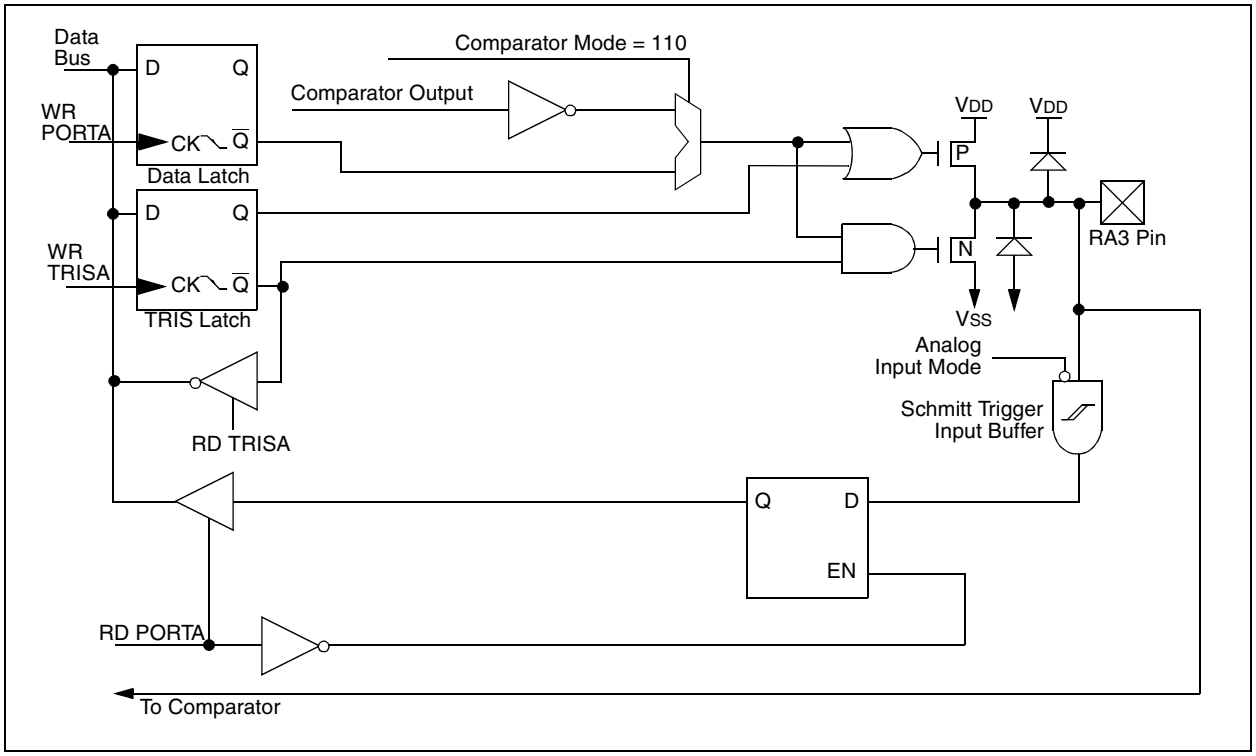
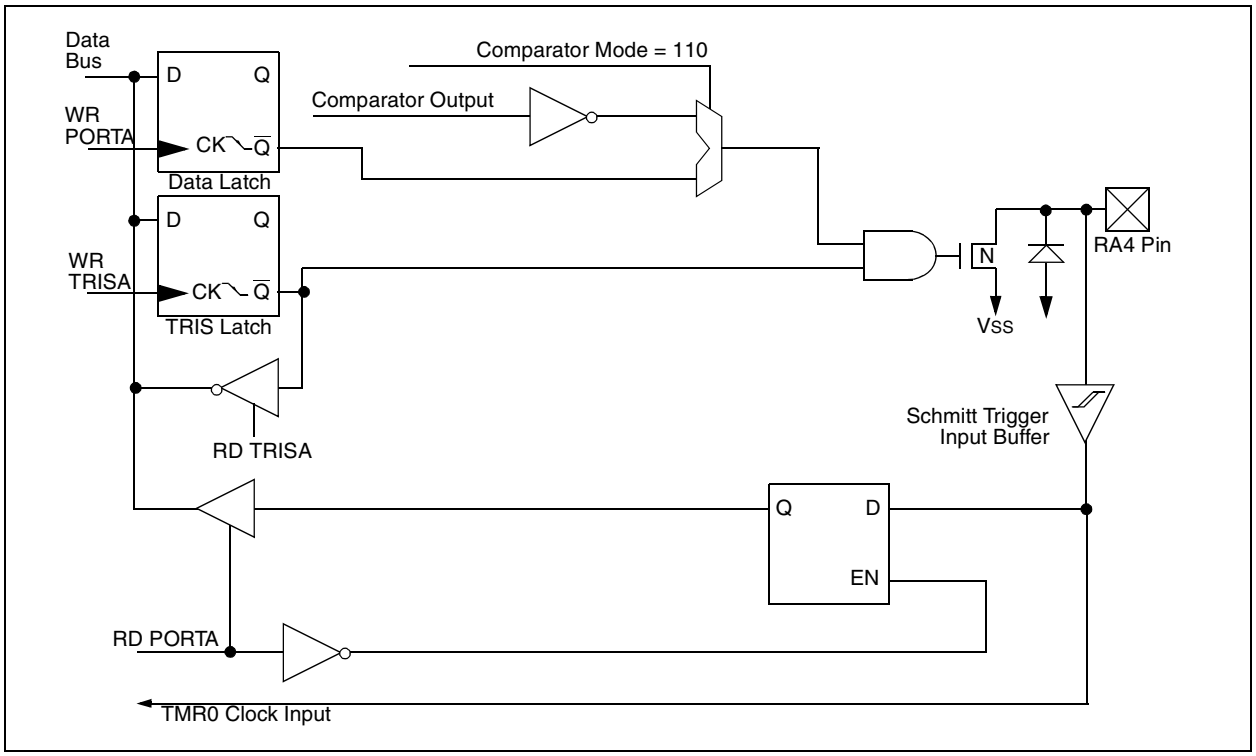


FIGURE 5-4: BLOCK DIAGRAM OF RA4 PIN



8.6 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of either comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<7:6>, to determine the actual change that has occurred. The CMIF bit, PIR1<6>, is the comparator interrupt flag. The CMIF bit must be reset by clearing '0'. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

The CMIE bit (PIE1<6>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit must also be set. If any of these bits are clear, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

Note:	If a change in the CMCON register (C1OUT or C2OUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR1<6>) interrupt flag may not get set.

The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of CMCON. This will end the mismatch condition.

b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition, and allow flag bit CMIF to be cleared.

8.7 Comparator Operation During SLEEP

When a comparator is active and the device is placed in SLEEP mode, the comparator remains active and the interrupt is functional if enabled. This interrupt will wake-up the device from SLEEP mode when enabled. While the comparator is powered-up, higher sleep currents than shown in the power down current specification will occur. Each comparator that is operational will consume additional current as shown in the comparator specifications. To minimize power consumption while in SLEEP mode, turn off the comparators, CM<2:0> = 111, before entering sleep. If the device wakes-up from sleep, the contents of the CMCON register are not affected.

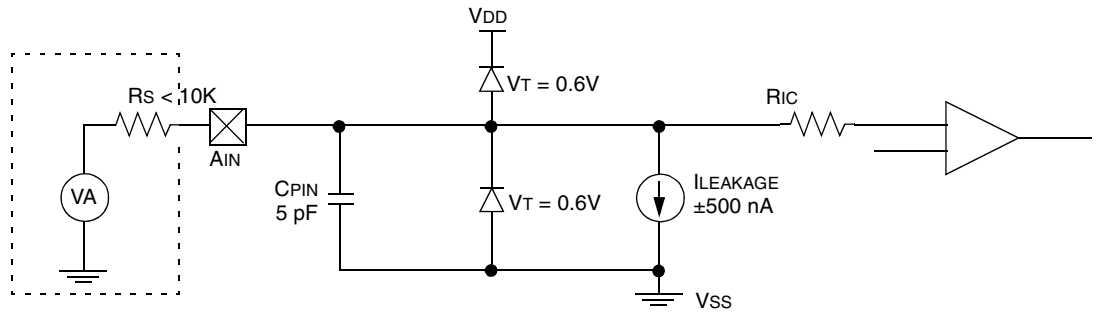
8.8 Effects of a RESET

A device reset forces the CMCON register to its reset state. This forces the comparator module to be in the comparator reset mode, CM<2:0> = 000. This ensures that all potential inputs are analog inputs. Device current is minimized when analog inputs are present at reset time. The comparators will be powered-down during the reset interval.

8.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 8-4. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and VSS. The analog input therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 8-4: ANALOG INPUT MODEL



Legend
CPIN = Input capacitance
VT = Threshold voltage
ILEAKAGE = Leakage current at the pin due to various junctions
RIC = Interconnect resistance
RS = Source impedance
VA = Analog voltage

EXAMPLE 9-1: VOLTAGE REFERENCE CONFIGURATION

```
MOVLW     0x02          ; 4 Inputs Muxed
MOVWF     CMCON         ; to 2 comps.
BSF       STATUS,RP0    ; go to Bank 1
MOVLW     0x07          ; RA3-RA0 are
MOVWF     TRISA         ; outputs
MOVLW     0xA6          ; enable VREF
MOVWF     VRCON         ; low range
                        ; set VR<3:0>=6
BCF       STATUS,RP0    ; go to Bank 0
CALL      DELAY10       ; 10µs delay
```

9.2 Voltage Reference Accuracy/Error

The full range of VSS to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 9-1) keep VREF from approaching VSS or VDD. The Voltage Reference is VDD derived and therefore, the VREF output changes with fluctuations in VDD. The absolute accuracy of the Voltage Reference can be found in Table 13-2.

9.3 Operation During Sleep

When the device wakes up from sleep through an interrupt or a Watchdog Timer time-out, the contents of the VRCON register are not affected. To minimize current consumption in SLEEP mode, the Voltage Reference should be disabled.

9.4 Effects of a Reset

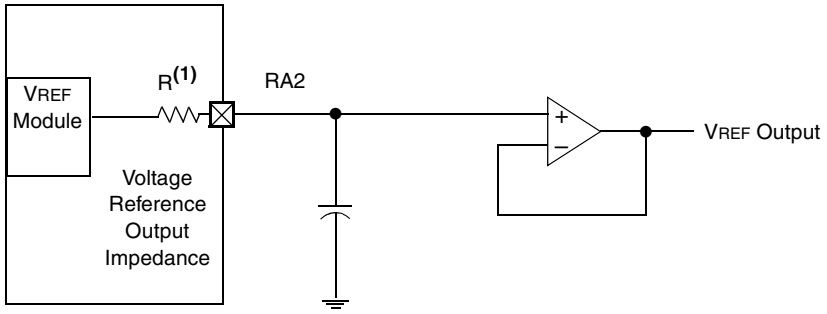
A device reset disables the Voltage Reference by clearing bit VREN (VRCON<7>). This reset also disconnects the reference from the RA2 pin by clearing bit VROE (VRCON<6>) and selects the high voltage range by clearing bit VRR (VRCON<5>). The VREF value select bits, VRCON<3:0>, are also cleared.

9.5 Connection Considerations

The Voltage Reference Module operates independently of the comparator module. The output of the reference generator may be connected to the RA2 pin if the TRISA<2> bit is set and the VROE bit, VRCON<6>, is set. Enabling the Voltage Reference output onto the RA2 pin with an input signal present will increase current consumption. Connecting RA2 as a digital output with VREF enabled will also increase current consumption.

The RA2 pin can be used as a simple D/A output with limited drive capability. Due to the limited drive capability, a buffer must be used in conjunction with the Voltage Reference output for external connections to VREF. Figure 9-2 shows an example buffering technique.

FIGURE 9-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE



Note 1: R is dependent upon the Voltage Reference Configuration VRCON<3:0> and VRCON<5>.

TABLE 9-1: REGISTERS ASSOCIATED WITH VOLTAGE REFERENCE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value On POR / BOD	Value On All Other Resets
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: - = Unimplemented, read as "0"

10.0 SPECIAL FEATURES OF THE CPU

Special circuits to deal with the needs of real time applications are what sets a microcontroller apart from other processors. The PIC16CE62X family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection.

These are:

1. OSC selection
2. Reset
   Power-on Reset (POR)
   Power-up Timer (PWRT)
   Oscillator Start-Up Timer (OST)
   Brown-out Reset (BOD)
3. Interrupts
4. Watchdog Timer (WDT)
5. SLEEP
6. Code protection
7. ID Locations
8. In-circuit serial programming

The PIC16CE62X has a Watchdog Timer which is controlled by configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, and is designed to keep the part in reset while the power supply stabilizes. There is also circuitry to reset the device if a brown-out occurs, which provides at least a 72 ms reset. With these three functions on-chip, most applications need no external reset circuitry.

The SLEEP mode is designed to offer a very low current power-down mode. The user can wake-up from SLEEP through external reset, Watchdog Timer wake-up or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost, while the LP crystal option saves power. A set of configuration bits are used to select various options.

10.4 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOD)

10.4.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in reset until VDD has reached a high enough level for proper operation. To take advantage of the POR, just tie the $\overline{MCLR}$ pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See electrical specifications for details.

The POR circuit does not produce an internal reset when VDD declines.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

For additional information, refer to Application Note AN607, “Power-up Trouble Shooting”.

10.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A configuration bit, $\overline{PWRTE}$, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should always be enabled when Brown-out Reset is enabled.

The Power-Up Time delay will vary from chip-to-chip and due to VDD, temperature and process variation. See DC parameters for details.

10.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-Up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on power-on reset or wake-up from SLEEP.

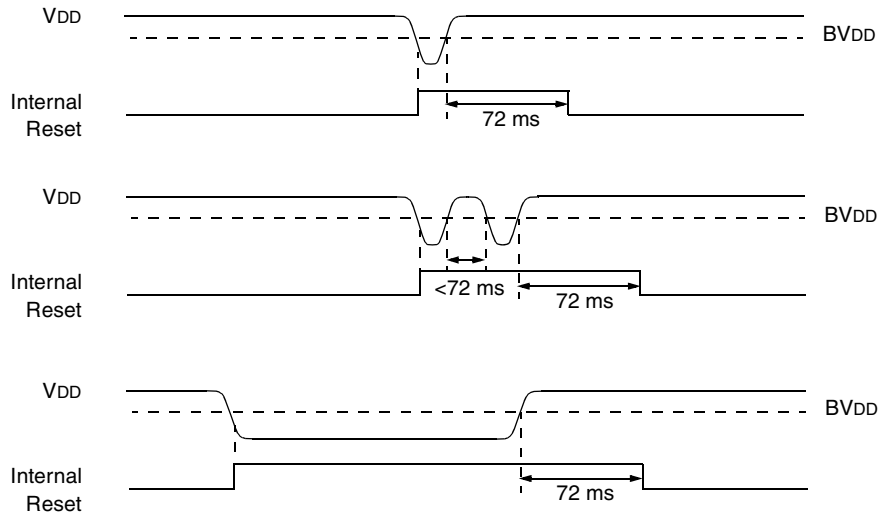
10.4.4 BROWN-OUT RESET (BOD)

The PIC16CE62X members have on-chip Brown-out Reset circuitry. A configuration bit, BOREN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V (refer to BVDD parameter D005) for greater than parameter (TBOR) in Table 13-5, the brown-out situation will reset the chip. A reset won’t occur if VDD falls below 4.0V for less than parameter (TBOR).

On any reset (Power-on, Brown-out, Watch-dog, etc.) the chip will remain in reset until VDD rises above BVDD. The Power-up Timer will then be invoked and will keep the chip in reset an additional 72 ms.

If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above BVDD, the Power-Up Timer will execute a 72 ms reset. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 10-7 shows typical Brown-out situations.

FIGURE 10-7: BROWN-OUT SITUATIONS



10.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{PD}$ bit in the STATUS register is cleared, the $\overline{TO}$ bit is set and the oscillator driver is turned off. The I/O ports maintain the status they had before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at V_{DD} or V_{SS}, with no external circuitry drawing current from the I/O pin, and the comparators and V_{REF} should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The $\overline{MCLR}$ pin must be at a logic high level (V_{IHMC}).

Note:	It should be noted that a RESET generated by a WDT time-out does not drive $\overline{MCLR}$ pin low.

10.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External reset input on $\overline{MCLR}$ pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

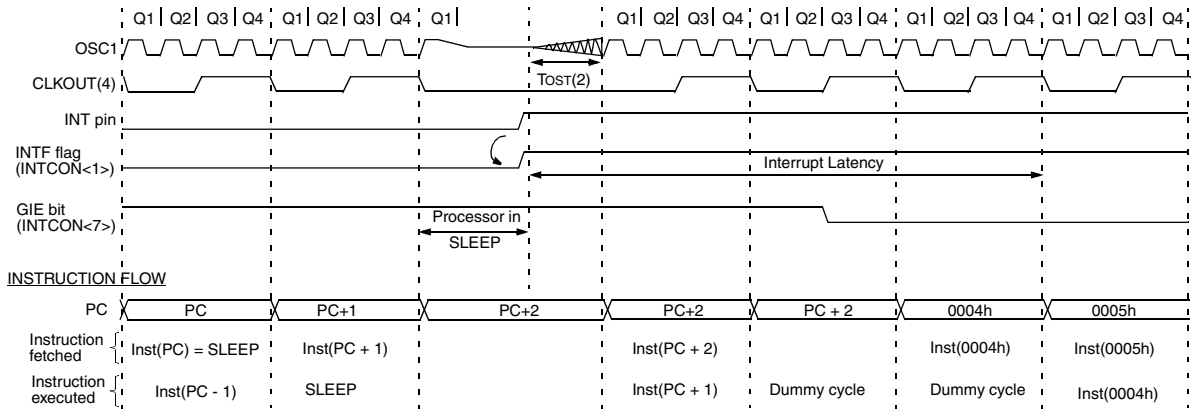
The first event will cause a device reset. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device reset. $\overline{PD}$ bit, which is set on power-up is cleared when SLEEP is invoked. $\overline{TO}$ bit is cleared if WDT wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note:	If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from sleep. The sleep instruction is completely executed.

The WDT is cleared when the device wakes-up from sleep, regardless of the source of wake-up.

FIGURE 10-19: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS or LP oscillator mode assumed.
2: TOST = 1024TOSC (drawing not to scale) This delay does not occur for RC osc mode.
3: GIE = '1' assumed. In this case after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

BCF **Bit Clear f**

Syntax: [*label*] BCF f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: $0 \rightarrow (f<b>)$

Status Affected: None

Encoding:

01	00bb	bfff	ffff

Description: Bit 'b' in register 'f' is cleared.

Words: 1

Cycles: 1

Example

```
BCF     FLAG_REG, 7
```

Before Instruction
FLAG_REG = 0xC7
After Instruction
FLAG_REG = 0x47

BSF **Bit Set f**

Syntax: [*label*] BSF f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: $1 \rightarrow (f<b>)$

Status Affected: None

Encoding:

01	01bb	bfff	ffff

Description: Bit 'b' in register 'f' is set.

Words: 1

Cycles: 1

Example

```
BSF     FLAG_REG,   7
```

Before Instruction
FLAG_REG = 0x0A
After Instruction
FLAG_REG = 0x8A

BTFSC **Bit Test, Skip if Clear**

Syntax: [*label*] BTFSC f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

01	10bb	bfff	ffff

Description: If bit 'b' in register 'f' is '0', then the next instruction is skipped.
If bit 'b' is '0', then the next instruction fetched during the current instruction execution is discarded, and a `NOP` is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example

```
HERE    BTFSC   FLAG,1
FALSE   GOTO    PROCESS_CODE
TRUE    •
        •
        •
```

Before Instruction
PC = address `HERE`
After Instruction
if FLAG<1> = 0,
PC = address `TRUE`
if FLAG<1>=1,
PC = address `FALSE`

13.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings †

Ambient Temperature under bias ..... -40° to +125°C

Storage Temperature ..... -65° to +150°C

Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$) ..... -0.6V to V_{DD} +0.6V

Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.0V

Voltage on RA4 with respect to V_{SS} 8.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) ..... 0 to +14V

Voltage on RA4 with respect to V_{SS} 8.5V

Total power Dissipation (Note 1) 1.0W

Maximum Current out of V_{SS} pin ..... 300 mA

Maximum Current into V_{DD} pin ..... 250 mA

Input Clamp Current, I_{IK} (V_I <0 or V_I> V_{DD}) ..... ±20 mA

Output Clamp Current, I_{OK} (V_O <0 or V_O>V_{DD}) ..... ±20 mA

Maximum Output Current sunk by any I/O pin ..... 25 mA

Maximum Output Current sourced by any I/O pin ..... 25 mA

Maximum Current sunk by PORTA and PORTB ..... 200 mA

Maximum Current sourced by PORTA and PORTB ..... 200 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100¾ should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† **NOTICE**: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

13.1 DC CHARACTERISTICS: PIC16CE62X-04 (Commercial, Industrial, Extended) PIC16CE62X-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature –40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	3.0	–	5.5	V	See Figure 13-1 through Figure 13-3
D002	VDR	RAM Data Retention Voltage (Note 1)	–	1.5*	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	–	VSS	–	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	–	–	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2, 4)	–	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)*
			–	0.4	1.2	mA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT osc mode, (Note 4)
			–	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS osc mode, (Note 6)
			–	4.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS osc mode
			–	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS osc mode
			–	35	70	µA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	–	–	2.2	µA	VDD = 3.0V
			–	–	5.0	µA	VDD = 4.5V*
			–	–	9.0	µA	VDD = 5.5V
			–	–	15	µA	VDD = 5.5V Extended
D022	ΔIWDT	WDT Current (Note 5)	–	6.0	10	µA	VDD = 4.0V
					12	µA	(125°C)
D022A	ΔIBOR	Brown-out Reset Current (Note 5)	–	75	125	µA	$\overline{BOD}$ enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator (Note 5)	–	30	60	µA	VDD = 4.0V
D023A	ΔIVREF	VREF Current (Note 5)	–	80	135	µA	VDD = 4.0V
	ΔIEE Write	Operating Current	–		3	mA	VCC = 5.5V, SCL = 400 kHz
	ΔIEE Read	Operating Current	–		1	mA	
	ΔIEE	Standby Current	–		30	µA	VCC = 3.0V, EE VDD = VCC
	ΔIEE	Standby Current	–		100	µA	VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency	0	–	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	–	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	–	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	–	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

13.3 DC CHARACTERISTICS: PIC16CE62X-04 (Commercial, Industrial, Extended) PIC16CE62X-20 (Commercial, Industrial, Extended) PIC16LCE62X (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature –40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and –40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range as described in DC spec Table 13-1				
Parm No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Unit**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports					
D030		with TTL buffer	VSS	–	0.8V 0.15VDD	V	VDD = 4.5V to 5.5V, Otherwise
D031		with Schmitt Trigger input	VSS		0.2VDD	V	
D032		$\overline{MCLR}$, RA4/T0CKI,OSC1 (in RC mode)	VSS	–	0.2VDD	V	Note1
D033		OSC1 (in XT and HS)	VSS	–	0.3VDD	V	
		OSC1 (in LP)	VSS	–	0.6VDD - 1.0	V	
	VIH	**Input High Voltage**					
		I/O ports					
D040		with TTL buffer	2.0V .25VDD + 0.8V	–	VDD VDD	V	VDD = 4.5V to 5.5V, Otherwise
D041		with Schmitt Trigger input	0.8VDD		VDD		
D042		$\overline{MCLR}$ RA4/T0CKI	0.8VDD	–	VDD	V	
D043		OSC1 (XT, HS and LP)	0.7VDD	–	VDD	V	
D043A		OSC1 (in RC mode)	0.9VDD				Note1
D070	IPURB	PORTB weak pull-up current	50	200	400	µA	VDD = 5.0V, VPIN = VSS
	IIL	**Input Leakage Current** (Notes 2, 3)					
		I/O ports (Except PORTA)			±1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D060		PORTA	–	–	±0.5	µA	Vss ≤ VPIN ≤ VDD, pin at hi-impedance
D061		RA4/T0CKI	–	–	±1.0	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1, $\overline{MCLR}$	–	–	±5.0	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	VOL	**Output Low Voltage**					
D080		I/O ports	–	–	0.6	V	IOL=8.5 mA, VDD=4.5V, -40° to +85°C
			–	–	0.6	V	IOL=7.0 mA, VDD=4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	–	–	0.6	V	IOL=1.6 mA, VDD=4.5V, -40° to +85°C
			–	–	0.6	V	IOL=1.2 mA, VDD=4.5V, +125°C
	VOH	**Output High Voltage** (Note 3)					
D090		I/O ports (Except RA4)	VDD-0.7	–	–	V	IOH=-3.0 mA, VDD=4.5V, -40° to +85°C
			VDD-0.7	–	–	V	IOH=-2.5 mA, VDD=4.5V, +125°C
D092		OSC2/CLKOUT (RC only)	VDD-0.7	–	–	V	IOH=-1.3 mA, VDD=4.5V, -40° to +85°C
			VDD-0.7	–	–	V	IOH=-1.0 mA, VDD=4.5V, +125°C
*D150	VOD	**Open-Drain High Voltage**			8.5	V	RA4 pin
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	Cio	All I/O pins/OSC2 (in RC mode)			50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16CE62X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

TABLE 13-1: COMPARATOR SPECIFICATIONS

Operating Conditions: VDD range as described in Table 12-1, -40°C<TA<+125°C. .

Param No.	Characteristics	Sym	Min	Typ	Max	Units	Comments
D300	Input offset voltage	VIOFF		± 5.0	± 10	mV	
D301	Input common mode voltage	VICM	0		VDD - 1.5	V	
D302	CMRR	CMRR	+55*			db	
300	Response Time(1)	TRESP		150*	400*	ns	PIC16CE62X
301	Comparator Mode Change to Output Valid	TMC2OV			10*	µs	

* These parameters are characterized but not tested.

Note 1: Response time measured with one comparator input at (VDD - 1.5)/2 while the other input transitions from VSS to VDD.

TABLE 13-2: VOLTAGE REFERENCE SPECIFICATIONS

Operating Conditions: VDD range as described in Table 12-1, -40°C<TA<+125°C.

Param No.	Characteristics	Sym	Min	Typ	Max	Units	Comments
D310	Resolution	VRES	VDD/24		VDD/32	LSB	
D311	Absolute Accuracy	VRAA			±1/4 ±1/2	LSB LSB	Low Range (VRR=1) High Range (VRR=0)
D312	Unit Resistor Value (R)	VRUR		2K*		Ω	Figure 9-1
310	Settling Time(1)	TSET			10*	µs	

* These parameters are characterized but not tested.

Note 1: Settling time measured while VRR = 1 and VR<3:0> transitions from 0000 to 1111.

APPENDIX A: CODE FOR ACCESSING EEPROM DATA MEMORY

Please check our web site at www.microchip.com for code availability.

APPENDIX B:REVISION HISTORY

Revision D (January 2013)

Added a note to each package outline drawing.

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